

01-20-04

2815

AMENDMENT TRANSMITTAL LETTER (Large Entity)

Applicant(s): Wen-Chun ZHENG et al.

Docket No.

03226.111001;P6259

Serial No.
10/085,183Filing Date
February 27, 2002Examiner
Chris C. ChuGroup Art Unit
2815Invention: **SOLID ASSEMBLY OF FLIP-CHIP PACKAGE ATTACHED TO HEAT REMOVAL DEVICE AND METHOD OF MANUFACTURING SAME**

JAN 16 2004

TO THE COMMISSIONER FOR PATENTS:

Transmitted herewith is an amendment in the above-identified application.

The fee has been calculated and is transmitted as shown below.

CLAIMS AS AMENDED

	CLAIMS REMAINING AFTER AMENDMENT	HIGHEST # PREV. PAID FOR	NUMBER EXTRA CLAIMS PRESENT	RATE	ADDITIONAL FEE
TOTAL CLAIMS	17 -	20 =	0	x \$18.00	\$0.00
INDEP. CLAIMS	3 -	3 =	0	x \$86.00	\$0.00
Multiple Dependent Claims (check if applicable)		<input type="checkbox"/>			\$0.00
		TOTAL ADDITIONAL FEE FOR THIS AMENDMENT			\$0.00

No additional fee is required for amendment.

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A check in the amount of to cover the filing fee is enclosed.

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Any additional filing fees required under 37 C.F.R. 1.16.

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Signature

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METHOD OF MANUFACTURING SAME**I hereby certify that this Response to Office Action*(Identify type of correspondence)*is being deposited with the United States Postal Service "Express Mail Post Office to Addressee" service under
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